

**CLAIMS**

What is claimed is:

1. An optoelectronic hermetic package, comprising:  
a frame defining a hermetic boundary; and  
an electrical feedthrough assembly on the frame 1) providing electrical connections  
between signal wire bond areas within the hermetic boundary and electrical  
contact areas outside the hermetic boundary and 2) ground wire bond areas  
within the hermetic boundary to each other.
2. A package as claimed in claim 1, further comprising an array of leads extending  
from electrical contact areas away from the frame.
3. A package as claimed in claim 2, wherein the leads extend laterally relative to the  
frame.
4. A package as claimed in claim 2, wherein the pins extend vertically relative to the  
frame.
5. A package as claimed in claim 1, wherein at least some of the ground wire bond  
areas are located between two of the signal wire bond areas on the feedthrough  
assembly.
6. A package as claimed in claim 1, wherein the ground wire bond areas are  
interdigitated with signal wire bond areas.
7. A package as claimed in claim 1, further comprising conductive plugs extending  
between a top of the feedthrough assembly and the frame, the ground wire bond areas  
being located on a top of the conductive plugs.

8. A package as claimed in claim 1, wherein the assembly provides electrical connections between the ground wire bond areas and the frame.

9. A package as claimed in claim 1, further comprising conductive plugs extending between a top of the feedthrough assembly and a bus through the assembly, the ground wire bond areas being located on a top of the conductive plugs.

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